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U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office

102429808

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies)

Chien-Wei Chang

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)

Name: Kinsus Interconnect Technology Corp.

Internal Address:

Street Address: No. 1245, Junghua Rd.

Shin-Wu Shiang

Taoyuan, Taiwan

City: State: ZIP:

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance:

- Assignment, Merger, Security Agreement, Change of Name, Other

Execution Date: April 11, 2003

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: April 11, 2003

A. Patent Application No.(s) 10414597 for "The Translation Pad Flip Chip (TPFC) Method For Improving Micro Bump Pitch IC Substrate Structure"

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Jason Z. Lin

Internal Address:

Supreme Patent Services

Street Address: Post Office Box 2339

City: Saratoga State: CA ZIP: 95070

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) \$ 40.00

- Enclosed, Authorized to be charged to deposit account

8. Deposit account number:

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Jason Z. Lin Name of Person Signing

Signature

4-15-2003 Date

Total number of pages including cover sheet, attachments, and document: 2

Mail documents to be recorded with required cover sheet information to: Commissioner of Patents & Trademarks, Box Assignments Washington, D.C. 20231

04/18/2003 MANNED1 00000034 10414597

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ASSIGNMENT

WHEREAS, I/we, Chien-Wei Chang
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful
improvements in THE TRANSLATION PAD FLIP CHIP (TPFC) METHOD FOR IMPROVING
MICRO BUMP PITCH SUBSTRATE STRUCTURE AND MANUFACTURING PROCESS
(hereinafter referred to as the Invention) for which an application for United States Letters Patent was

- executed on even date herewith;
- executed on _____;
- filed on _____, Serial No. _____;
- filed as PCT International Application No. _____ on _____, designating
The United States of America;
- Patent number _____, issue on _____.

WHEREAS, Kinsus Interconnect Technology Corp.
whose post office address is No.1245, Junghua Rd., Shin-Wu Shiang, Taoyuan, Taiwan, R.O.C.
hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United
States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I/we, ASSIGNOR,
by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said invention
and application throughout the United States of America, including any and all Letters Patent granted on any division,
continuation, continuation-in-part and reissue of said application.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing,
prosecution and maintenance of said application or any other patent application(s) in the United States for said invention,
including additional documents that may be required to affirm the rights of ASSIGNEE in and to said invention, all without
further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE's expense, to identify and
communicate to ASSIGNEE at ASSIGNEE's request documents and information concerning the invention that are within
ASSIGNOR's possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may
be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent
encompassed within the terms of this instrument. ASSIGNOR's obligations under this instrument shall extend to ASSIGNOR's
heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters
Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for
ASSIGNEE's sole use and behoof; and for the use and behoof of ASSIGNEE's legal representatives and successors, to the full
end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by
ASSIGNOR had this assignment and sale not been made.

Assignor: Chien-Wei Chang Dated this 11th day of Apr., 2003 at Taiwan, R. O. C.
No.1245, Junghua Rd., Shin-
Wu Shiang, Taoyuan,
Taiwan, R.O.C.

Chang Chien Wei

Signature

Assignor: Dated this _____ day of _____ at Taiwan, R. O. C.

Signature

Assignor: Dated this _____ day of _____ at Taiwan, R. O. C.

Signature